

Hybrid and HDI Chip Components

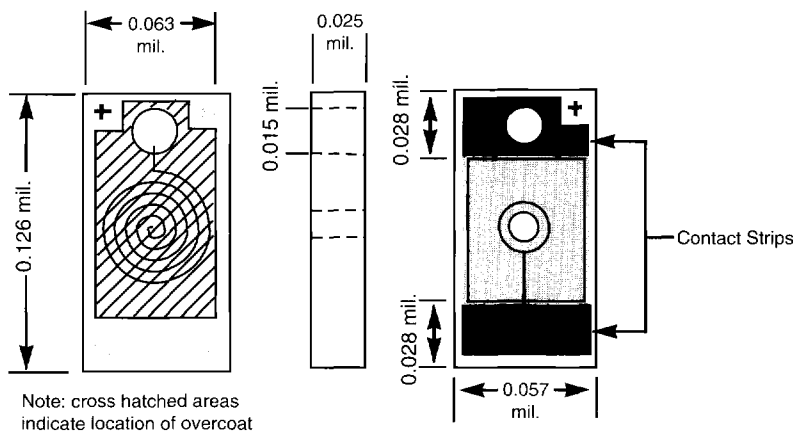
Chip Inductors

General

Electro-Films, Inc. manufactures a line of high frequency inductors in the range of 2 to 1000 nanohenries. Versions are available in standard chip and wire, flip chip, and face-up mounting configurations. Inductors are overcoated with polyimide for surface protection. The center contact can be brought to the outside edge through the use of a polyimide insulating bridge where required. Standard chip sizes and configurations are available but because applications often require specific values, the inductance and Q requirements are generally tailored to the customer's needs. Considerable effort has been made by EFI to develop appropriate software to produce desired values.

In addition to standard sizes, the inductors can be supplied in custom sizes depending on inductance value and customer preference and requirements.

Mechanical Parameters, Standard L11 Series

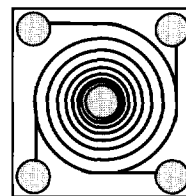
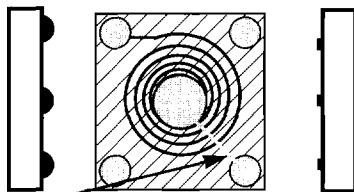


Custom Mechanical Options

FLIP CHIP SIDE VIEW

WIREBOND SIDE VIEW

Multi-tapped Version
(patent pending)



Polyimide Supported Bridge
optional for wire bond versions < 100 mil.

Descriptive Part Number

Example: 6.75 nanohenries, Q = 40 min. @ 300 mhz, 120 mil. x 165 mil. face up attachment

P/N: S - L11 - 675 x B - 040 @ 300 - 120 - 165 - FU

L Series
Inductance (3 significant digits)

Code = Multiplier
C = 0.001
B = 0.01
A = 0.1
0 = 1.0

Q

Frequency (mhz)

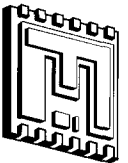
Length (mil.)

Width (mil.)

Configuration
CW = Chip & Wire
FC = Flip Chip
FU = Face Up

Inspection/Packaging

R = 100% visual, 100% Inductance & resistance, Sample Q (1% AQL)
S = 100% visual, 100% Inductance & Sample Q and Resistance (1% AQL)
T = 100% visual, Sample Inductance, Q and resistance, (1% AQL)
V = Sample visual, Inductance, Q D, C resistance, (1% AQL)



Electro-Films Inc.